# MOSFET - Small Signal, Complementary, SC-88 20 V / -8.0 V, +0.63 A / -0.775 A

#### **Features**

- Complementary N and P Channel Device
- Leading -8.0 V Trench for Low R<sub>DS(on)</sub> Performance
- ESD Protected Gate ESD Rating: Class 1
- SC-88 Package for Small Footprint (2 x 2 mm)
- Pb-Free Packages are Available

#### **Applications**

- DC-DC Conversion
- Load/Power Switching
- Single or Dual Cell Li-Ion Battery Supplied Devices
- Cell Phones, MP3s, Digital Cameras, PDAs

### **MAXIMUM RATINGS** ( $T_J = 25^{\circ}C$ unless otherwise noted)

Paramet	Symbol	Value	Unit		
Drain-to-Source Voltage	N-Ch	$V_{DSS}$	20	V	
	P-Ch		-8.0		
Gate-to-Source Voltage		N-Ch	$V_{GS}$	±12	V
		P-Ch		±8.0	
Continuous Drain Current	N-Ch	T <sub>A</sub> = 25°C	I <sub>D</sub>	0.63	Α
– Steady State (Based on R <sub>0.IA</sub> )		T <sub>A</sub> = 85°C		0.46	
(Васса от гада)	P-Ch	T <sub>A</sub> = 25°C		-0.775	
		T <sub>A</sub> = 85°C		-0.558	
Continuous Drain Current	N-Ch	T <sub>A</sub> = 25°C		0.91	
– Steady State (Based on $R_{\theta JL}$ )		T <sub>A</sub> = 85°C		0.65	
	P-Ch	T <sub>A</sub> = 25°C		-1.1	
		T <sub>A</sub> = 85°C		-0.8	
Pulsed Drain Current	tp ≤ 10 μs	I <sub>DM</sub>	±1.2	Α	
	Power Dissipation - Steady State			0.27	W
(Based on R <sub>θJA</sub> )		T <sub>A</sub> = 85°C		0.14	
Power Dissipation - Steady	/ State	T <sub>A</sub> = 25°C		0.55	
(Based on $R_{\theta JL}$ )		T <sub>A</sub> = 85°C		0.29	
Operating Junction and Sto	T <sub>J</sub> , T <sub>STG</sub>	–55 to 150	°C		
Source Current (Body Diod	N-Ch	I <sub>S</sub>	0.63	Α	
	P-Ch		-0.775		
Lead Temperature for Sold (1/8" from case for 10 s	TL	260	°C		

#### THERMAL RESISTANCE RATINGS (Note 1)

Junction-to-Ambient	Тур	$R_{\theta JA}$	400	°C/W
<ul><li>Steady State</li></ul>	Max		460	
Junction-to-Lead (Drain)	Тур	$R_{\theta JL}$	194	
<ul><li>Steady State</li></ul>	Max		226	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

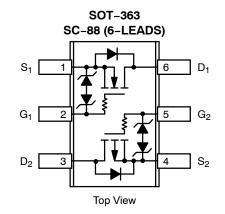
1. Surface mounted on FR4 board using 1 oz Cu area = 0.9523 in sq.



#### ON Semiconductor®

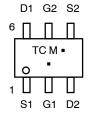
#### http://onsemi.com

V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> TYP	I <sub>D</sub> Max
N-Ch 20 V	0.29 Ω @ 4.5 V	
	0.36 Ω @ 2.5 V	0.63 A
	0.22 Ω @ -4.5 V	
P-Ch -8.0 V	0.32 Ω @ -2.5 V	-0.775 A
	0.51 Ω @ –1.8 V	



# MARKING DIAGRAM & PIN ASSIGNMENT





TC = Device Code

M = Date Code

Pb-Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 7 of this data sheet.

#### **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub> = 25°C unless otherwise noted)

ELECTRICAL CHARACTER		N/D	Took Condition		N4:	T	Mari	I I a ida
Parameter	Symbol	N/P	Test Condition	on	Min	Тур	Max	Units
OFF CHARACTERISTICS								
Drain-to-Source	$V_{(BR)DSS}$	N	V <sub>GS</sub> = 0 V	$I_D = 250  \mu A$	20	27		V
Breakdown Voltage		Р	VGS - V	$I_D = -250  \mu A$	-8.0	-10.5		
Drain-to-Source Breakdown	V <sub>(BR)DSS</sub>	N				22		mV/ °C
Voltage Temperature Coefficient	/TJ	P				-6.0		1
		N.	\/ 0\/\/ 40\/				4.0	
Zero Gate Voltage Drain Cur- rent	IDSS	N	$V_{GS} = 0 \text{ V}, V_{DS} = 16 \text{ V}$	T <sub>J</sub> = 25 °C			1.0	μΑ
		P	$V_{GS} = 0 \text{ V}, V_{DS} = -6.4 \text{ V}$	\/ \doldown			1.0	
Gate-to-Source Leakage Current	I <sub>GSS</sub>	N P	$V_{DS} = 0 V$	$V_{GS} = \pm 12 \text{ V}$			10	μΑ
	<b>.</b>	Р		$V_{GS} = \pm 8.0$		<u>l</u>	10	
ON CHARACTERISTICS (Note 2	-	l NI		1 050 A	0.0	0.00	1 4 5	1 1/
Gate Threshold Voltage	V <sub>GS(TH)</sub>	N P	$V_{GS} = V_{DS}$	I <sub>D</sub> = 250 μA	0.6	0.92	1.5	V
Cata Thuashald	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \			$I_D = -250 \mu\text{A}$	-0.45	-0.83	-1.0	\// 00
Gate Threshold Temperature Coefficient	V <sub>GS(TH)</sub> /	N P				-2.1		-mV/ °C
•	ŭ	-	\/ 45\/1 /	2.00.4		2.2	0.075	0
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	N P	$V_{GS} = 4.5 \text{ V I}_{D} = 0$			0.29	0.375	Ω
			$V_{GS} = -4.5 \text{ V}, I_D = -4.5 \text{ V}$			0.22	0.30	-
		N P	$V_{GS} = 2.5 \text{ V}, I_D = 0.5 \text{ V}$			0.36	0.445 0.46	
		P	$V_{GS} = -2.5 \text{ V}, I_D = -2.5 \text{ V}$			0.32		
Forward Transponductors	-		$V_{GS} = -1.8 \text{ V}, I_D = -1.8 \text{ V}$			0.51	0.90	S
Forward Transconductance	9FS	N P	$V_{DS} = 4.0 \text{ V } I_{D} = 0.63 \text{ A}$ $V_{DS} = -4.0 \text{ V, } I_{D} = -0.57 \text{ A}$			2.0		8
			$v_{DS} = -4.0 \text{ v}, i_D = -4.0 \text{ v}$	-0.57 A		2.0		
CHARGES AND CAPACITANCE							- 40	
Input Capacitance	C <sub>ISS</sub>	N		V <sub>DS</sub> = 20 V		33	46	pF
0.1-10		P		$V_{DS} = -8.0V$		160	225	
Output Capacitance	C <sub>OSS</sub>	N	f = 1 MHz, V <sub>GS</sub> = 0 V	V <sub>DS</sub> = 20 V		13	22	
D. T. C. C. C. C.	0	P		$V_{DS} = -8.0 \text{ V}$		38	55	
Reverse Transfer Capacitance	C <sub>RSS</sub>	N		V <sub>DS</sub> = 20 V		2.8	5.0	
Total Cata Obarra		P	\\\\ 45\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	$V_{DS} = -8.0 \text{ V}$		28	40	-0
Total Gate Charge	$Q_{G(TOT)}$	N P	$V_{GS} = 4.5 \text{ V}, V_{DS} = 10 \text{ V}$			1.3	3.0	nC
Threshold Cata Charge		N	$V_{GS} = -4.5 \text{ V}, V_{DS} = -5.0$			2.2	4.0	ļ
Threshold Gate Charge	Q <sub>G(TH)</sub>	P	$V_{GS} = 4.5 \text{ V}, V_{DS} = 10 \text{ V}$			0.1		
Gate-to-Source Charge	0	N	$V_{GS} = -4.5 \text{ V}, V_{DS} = -5.0$ $V_{GS} = 4.5 \text{ V}, V_{DS} = 10 \text{ V}$			0.1		
Gale-10-30urce Charge	Q <sub>GS</sub>	P	$V_{GS} = 4.5 \text{ V}, V_{DS} = 10 \text{ V}$ $V_{GS} = -4.5 \text{ V}, V_{DS} = -5.0 \text{ V}$			0.2		
Gate-to-Drain Charge	Q <sub>GD</sub>	N	$V_{GS} = -4.5 \text{ V}, V_{DS} = -5.0 \text{ V}$ $V_{GS} = 4.5 \text{ V}, V_{DS} = 10 \text{ V}$			0.5		
Gate-to-Diam Charge	QGD	P	$V_{GS} = -4.5 \text{ V}, V_{DS} = -5.0$			0.4		ł
SWITCHING CHARACTERISTIC	S (Note 3)		vGS+.5 v, vDS = -5.0	v, iD – -0.0 A		0.5	I	l
Turn-On Delay Time	. ,	N				0.083	l	μs
Rise Time	t <sub>d(ON)</sub>	'`	\/15\/\/	- 10 V		0.083	<b> </b>	μο
Turn-Off Delay Time	tross	l	$V_{GS} = 4.5 \text{ V}, V_{DD} = I_D = 0.5 \text{ A}, R_G = 0.5 \text{ A}$	= 10 v, 20 Ω		0.786		1
Fall Time	t <sub>d(OFF)</sub>	ł	. <sub>D</sub> 3.37.,.1d =	<del></del>		0.786	-	ĺ
Turn-On Delay Time	t <sub>f</sub>	Р				0.013		1
Rise Time	t <sub>d(ON)</sub>	'	V <sub>GS</sub> = -4.5 V, V <sub>DD</sub> =	4 0 V		0.013		1
Turn-Off Delay Time	1	1	$V_{GS} = -4.5 \text{ V}, V_{DD} = 1_{D} = -0.5 \text{ A}, R_{G} = 1_{D} = -0.5 \text{ A}$	8.0 Ω		0.050		1
Fall Time	t <sub>d(OFF)</sub>	1	, ·u			0.036		1
DRAIN-SOURCE DIODE CHAR	<u> </u>	CS				0.000	1	I
Forward Diode Voltage	V <sub>SD</sub>	N		I <sub>S</sub> = 0.23 A		0.76	1.1	V
	*80	P	$V_{GS} = 0 \text{ V}, T_J = 25^{\circ}\text{C}$	$I_S = 0.23 \text{ A}$ $I_S = -0.23 \text{ A}$		0.76	1.1	l ,
		N		$I_S = 0.23 \text{ A}$		0.63		1
		P	$V_{GS} = 0 \text{ V}, T_{J} = 125^{\circ}\text{C}$	$I_S = 0.23 \text{ A}$ $I_S = -0.23 \text{ A}$		0.63	-	ł
Reverse Recovery Time	t <sub>RR</sub>	N	\/ O\/	$I_S = -0.23 \text{ A}$ $I_S = 0.23 \text{ A}$		0.410		μS
Tio Color Tio Covery Time	HH	P	$V_{GS} = 0 \text{ V},$ $d_{IS}/d_{t} = 90 \text{ A}/\mu \text{s}$	$I_S = 0.23 \text{ A}$ $I_S = -0.23 \text{ A}$		0.410		μο
			=10/=L 00/4/pi0	.S = 0.20 A		0.070		

Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.
 Switching characteristics are independent of operating junction temperatures.

#### TYPICAL N-CHANNEL PERFORMANCE CURVES (T<sub>J</sub> = 25°C unless otherwise noted)

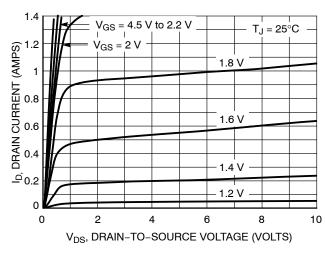


Figure 1. On-Region Characteristics

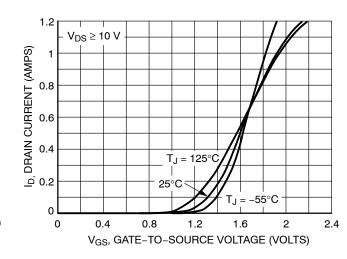


Figure 2. Transfer Characteristics

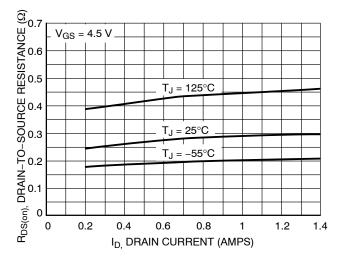


Figure 3. On-Resistance vs. Drain Current and Temperature

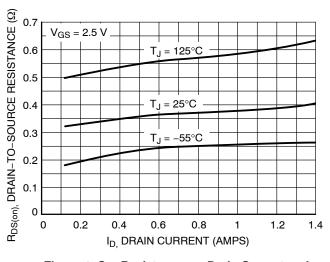


Figure 4. On-Resistance vs. Drain Current and Temperature

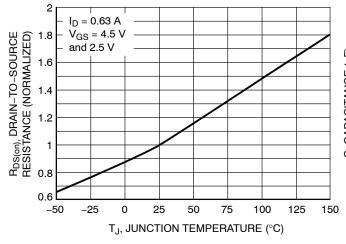


Figure 5. On–Resistance Variation with Temperature

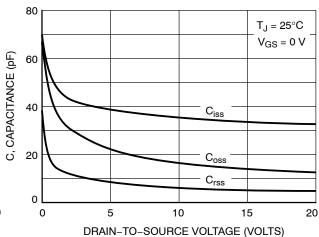


Figure 6. Capacitance Variation

# TYPICAL N-CHANNEL PERFORMANCE CURVES ( $T_J = 25$ °C unless otherwise noted)

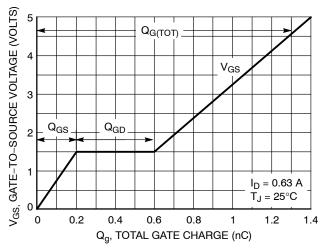


Figure 7. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

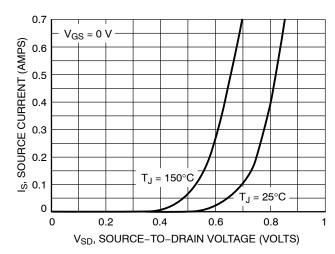


Figure 8. Diode Forward Voltage vs. Current

#### TYPICAL P-CHANNEL PERFORMANCE CURVES (T<sub>J</sub> = 25°C unless otherwise noted)

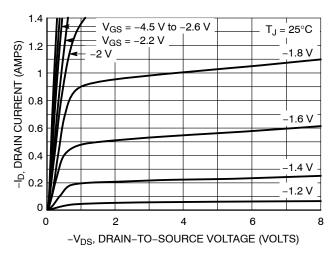


Figure 9. On-Region Characteristics

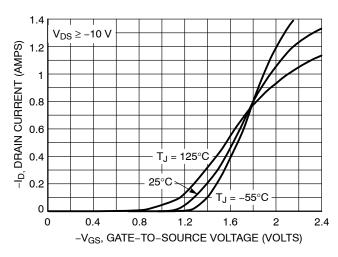


Figure 10. Transfer Characteristics

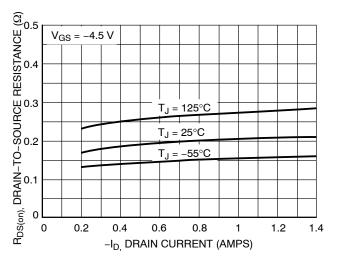


Figure 11. On–Resistance vs. Drain Current and Temperature

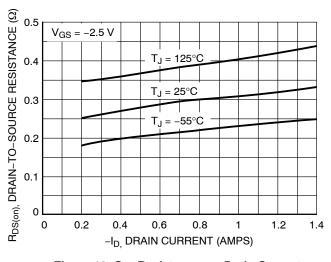


Figure 12. On-Resistance vs. Drain Current and Temperature

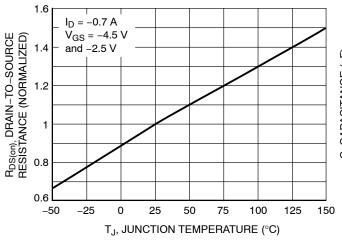


Figure 13. On–Resistance Variation with Temperature

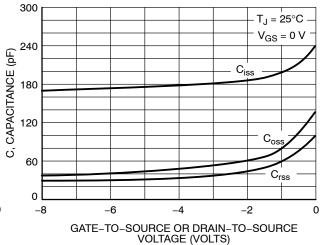


Figure 14. Capacitance Variation

# TYPICAL P-CHANNEL PERFORMANCE CURVES ( $T_J = 25$ °C unless otherwise noted)

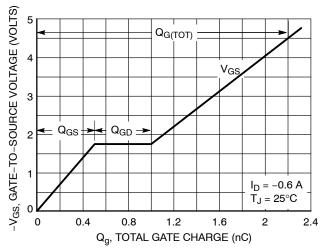


Figure 15. Gate-to-Source and Drain-to-Source Voltage vs. Total Charge

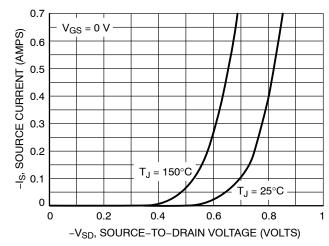


Figure 16. Diode Forward Voltage vs. Current

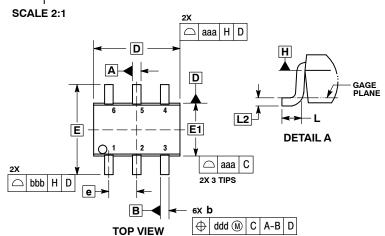
#### **ORDERING INFORMATION**

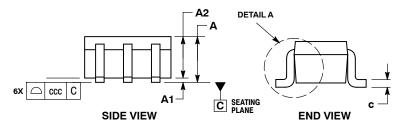
Device	Package	Shipping <sup>†</sup>
NTJD4105CT1	SOT-363	3000 / Tape & Reel
NTJD4105CT1G	SOT-363 (Pb-Free)	3000 / Tape & Reel
NTJD4105CT2	SOT-363	3000 / Tape & Reel
NTJD4105CT2G	SOT-363 (Pb-Free)	3000 / Tape & Reel
NTJD4105CT4	SOT-363	10,000 / Tape & Reel
NTJD4105CT4G	SOT-363 (Pb-Free)	10,000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### SC-88/SC70-6/SOT-363 CASE 419B-02 **ISSUE Y**

**DATE 11 DEC 2012** 





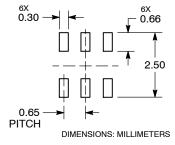
# NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
   CONTROLLING DIMENSION: MILLIMETERS
- CONTROLLING DIMENSION: MILLIMETERS.
  DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH,
- DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.20 PER END. DIMENSIONS D AND E1 AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY AND DATUM H. DATUMS A AND B ARE DETERMINED AT DATUM H. DIMENSIONS b AND c APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.08 AND 0.15 FROM THE TIP.

- DIMENSION & DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF DIMENSION 6 AT MAXIMUM MATERIAL CONDITION. THE DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT.

	MIL	LIMETE	RS		INCHES	3		
DIM	MIN	NOM	MAX	MIN	NOM	MAX		
Α			1.10			0.043		
A1	0.00		0.10	0.000		0.004		
A2	0.70	0.90	1.00	0.027	0.035	0.039		
b	0.15	0.20	0.25	0.006	0.008	0.010		
С	0.08	0.15	0.22	0.003	0.006	0.009		
D	1.80	2.00	2.20	0.070	0.078	0.086		
E	2.00	2.10	2.20	0.078	0.082	0.086		
E1	1.15	1.25	1.35	0.045	0.049	0.053		
е		0.65 BS	С	0	.026 BS	026 BSC		
L	0.26	0.36	0.46	0.010	0.014	0.018		
L2		0.15 BS	C		0.006 BS	SC		
aaa		0.15			0.006			
bbb		0.30			0.012			
ccc		0.10			0.004			
ddd		0.10			0.004			

#### **RECOMMENDED SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### **GENERIC MARKING DIAGRAM\***



XXX = Specific Device Code

= Date Code\* = Pb-Free Package

(Note: Microdot may be in either location)

- \*Date Code orientation and/or position may vary depending upon manufacturing location.
- \*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

#### **STYLES ON PAGE 2**

DOCUMEN	IT NUMBER:	98ASB42985B	Electronic versions are uncontrolled except when accessed directly from the Document Reposi Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.			
DE	SCRIPTION:	SC-88/SC70-6/SOT-363		PAGE 1 OF 2		

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#### SC-88/SC70-6/SOT-363 CASE 419B-02 ISSUE Y

**DATE 11 DEC 2012** 

STYLE 1: PIN 1. EMITTER 2 2. BASE 2 3. COLLECTOR 1 4. EMITTER 1 5. BASE 1 6. COLLECTOR 2	STYLE 2: CANCELLED	STYLE 3: CANCELLED	STYLE 4: PIN 1. CATHODE 2. CATHODE 3. COLLECTOR 4. EMITTER 5. BASE 6. ANODE	STYLE 5: PIN 1. ANODE 2. ANODE 3. COLLECTOR 4. EMITTER 5. BASE 6. CATHODE	STYLE 6: PIN 1. ANODE 2 2. N/C 3. CATHODE 1 4. ANODE 1 5. N/C 6. CATHODE 2
STYLE 7: PIN 1. SOURCE 2 2. DRAIN 2 3. GATE 1 4. SOURCE 1 5. DRAIN 1 6. GATE 2	STYLE 8: CANCELLED	STYLE 9: PIN 1. EMITTER 2 2. EMITTER 1 3. COLLECTOR 1 4. BASE 1 5. BASE 2 6. COLLECTOR 2	STYLE 10: PIN 1. SOURCE 2 2. SOURCE 1 3. GATE 1 4. DRAIN 1 5. DRAIN 2 6. GATE 2	STYLE 11: PIN 1. CATHODE 2 2. CATHODE 2 3. ANODE 1 4. CATHODE 1 5. CATHODE 1 6. ANODE 2	STYLE 12: PIN 1. ANODE 2 2. ANODE 2 3. CATHODE 1 4. ANODE 1 5. ANODE 1 6. CATHODE 2
STYLE 13: PIN 1. ANODE 2. N/C 3. COLLECTOR 4. EMITTER 5. BASE 6. CATHODE	STYLE 14: PIN 1. VREF 2. GND 3. GND 4. IOUT 5. VEN 6. VCC	STYLE 15: PIN 1. ANODE 1 2. ANODE 2 3. ANODE 3 4. CATHODE 3 5. CATHODE 2 6. CATHODE 1	STYLE 16: PIN 1. BASE 1 2. EMITTER 2 3. COLLECTOR 2 4. BASE 2 5. EMITTER 1 6. COLLECTOR 1	STYLE 17: PIN 1. BASE 1 2. EMITTER 1 3. COLLECTOR 2 4. BASE 2 5. EMITTER 2 6. COLLECTOR 1	STYLE 18: PIN 1. VIN1 2. VCC 3. VOUT2 4. VIN2 5. GND 6. VOUT1
STYLE 19: PIN 1. I OUT 2. GND 3. GND 4. V CC 5. V EN 6. V REF	STYLE 20: PIN 1. COLLECTOR 2. COLLECTOR 3. BASE 4. EMITTER 5. COLLECTOR 6. COLLECTOR	STYLE 21: PIN 1. ANODE 1 2. N/C 3. ANODE 2 4. CATHODE 2 5. N/C 6. CATHODE 1	STYLE 22: PIN 1. D1 (i) 2. GND 3. D2 (i) 4. D2 (c) 5. VBUS 6. D1 (c)	STYLE 23: PIN 1. Vn 2. CH1 3. Vp 4. N/C 5. CH2 6. N/C	STYLE 24: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE
STYLE 25: PIN 1. BASE 1 2. CATHODE 3. COLLECTOR 2 4. BASE 2 5. EMITTER 6. COLLECTOR 1	STYLE 26: PIN 1. SOURCE 1 2. GATE 1 3. DRAIN 2 4. SOURCE 2 5. GATE 2 6. DRAIN 1	STYLE 27: PIN 1. BASE 2 2. BASE 1 3. COLLECTOR 1 4. EMITTER 1 5. EMITTER 2 6. COLLECTOR 2	STYLE 28: PIN 1. DRAIN 2. DRAIN 3. GATE 4. SOURCE 5. DRAIN 6. DRAIN	STYLE 29: PIN 1. ANODE 2. ANODE 3. COLLECTOR 4. EMITTER 5. BASE/ANODE 6. CATHODE	STYLE 30: PIN 1. SOURCE 1 2. DRAIN 2 3. DRAIN 2 4. SOURCE 2 5. GATE 1 6. DRAIN 1

Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

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